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10580740 Rec'd PTO 26 MAY 2006

Date of Deposit: May 26, 2006

Case No. 10808/330 (In1344WOUS)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HELNEDER et al.

Serial No.: Not Yet Assigned

Filing Date: Herewith

For METHOD FOR ELECTROPLATING
AND CONTACT PROJECTION
ARRANGEMENT

Examiner:

Not Yet Assigned

Group Art Unit No.:

Not Yet Assigned

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

Dear Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and §§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(b), Applicants hereby cite the following references:

| DOCUMENT NUMBER | DATE/ DATE OF PUBLICATION | NAME/COUNTRY |
|--------------------|------------------------------|---------------|
| US 2004/0018660 A1 | 01/29/2004 | Kim et al. |
| US 2002/0072215 A1 | 06/13/2002 | Furuya |
| 6,316,831 B1 | 11/13/2001 | Wang |
| WO 03/044246 A1 | 05/30/2006 | PCT |
| EP 1 148 548 A2 | 10/24/2001 | EPO |
| EP 0 547 815 B1 | 03/12/1997 | EPO |
| EP 0 261 799 A1 | 03/30/1988 | EPO |
| FR 2 502 399 | 09/24/1982 | France |
| GB 2 095 904 A | 10/06/1982 | Great Britain |
| 02224336 | 09/06/1990 | Japan |
| 56105653 | 08/22/1981 | Japan |

OTHER ART

Jang et al., "CrCu Based UBM (Under Bump Metallization) Study With Electroplated Pb/63Sn Solder Bumps-Interfacial Reaction and Bump Shear Strength," IEEE Transactions on Components and Packaging Technologies, Vol. 26, No. 1, March 2003, pp. 245-254.

Reid et al., "Factors Influencing Damascene Feature Fill Using Copper PVD and Electroplating," *Solid State Technology*, July 2000, pp. 86-88, 92, 96, 98, 103.

BRINKS
HOFFER
GILSON
& LIONE

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /L.V./

100580347/640: 1795
MAY 2006

Applicants are enclosing Form PTO-1449 (one sheet), along with a copy of cited references A4-A13. Applicants respectfully request the Examiner's consideration of the above references and entry thereof into the record of this application.

Also enclosed is a copy of an Office Action dated July 27, 2004 from the corresponding German Application (in the German language).

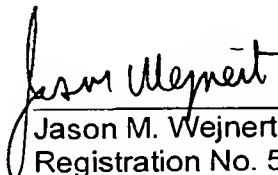
Also enclosed is a copy of the International Search Report dated March 1, 2005 for the corresponding PCT Application No. WO2004/052999.

FR 2 502 399 discloses a semiconductor device having low resistance connection to a portion thereof carrying substantial current. A non-certified English translation of the Abstract is enclosed herewith. Applicants have also cited corresponding Great Britain Patent No. 2 095 904 A.

By submitting this Statement, Applicants are attempting to fully comply with the duty of candor and good faith mandated by 37 C.F.R. §1.56. As such, this Statement is not intended to constitute an admission that any of the enclosed references, or other information referred to therein, constitutes "prior art" or is otherwise "material to patentability," as that phrase is defined in 37 C.F.R. §1.56(a).

Applicants have calculated no fee to be due in connection with the filing of this Statement. However, the Director is authorized to charge any fee deficiency associated with the filing of this Statement to a deposit account, as authorized in the Transmittal accompanying this Statement.

Respectfully submitted,



Jason M. Wejnert
Registration No. 55,722
Attorney for Applicants

BRINKS HOFER GILSON & LIONE
P.O. BOX 10395
CHICAGO, ILLINOIS 60610
(312) 321-4200

BRINKS
HOFFER
GILSON
& LIONE

1AP20 Rec'd PCT/PTO 26 MAY 2006

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| FORM PTO-1449 | SERIAL NO. Not Yet Assigned | CASE NO. 10808/330 In 1344 WO/US |
| LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT | FILING DATE May 26, 2006 | GROUP ART UNIT Not Yet Assigned |
| APPLICANTS: Helneder et | | |

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | | DOCUMENT NUMBER <small>Number-Kind Code (if known)</small> | DATE | NAME | CLASS/ SUBCLASS | FILING DATE |
|---------------------|----|--|------------|------------|--------------------|----------------|
| | A1 | US 2004/0018660 A1 | 01/29/2004 | Kim et al. | | |
| | A2 | US 2002/0072215 A1 | 06/13/2002 | Furuya | | |
| | A3 | 6,316,831 B1 | 11/13/2001 | Wang | | |

FOREIGN PATENT DOCUMENTS

| EXAMINER INITIAL | | DOCUMENT NUMBER <small>Number-Kind Code (if known)</small> | DATE | COUNTRY | CLASS/ SUBCLASS | TRANSLATION YES OR NO |
|---------------------|-----|--|------------|---------------|--------------------|--------------------------|
| | A4 | WO 03/044246 A1 | 05/30/2006 | PCT | | |
| | A5 | EP 1 148 548 A2 | 10/24/2001 | EPO | | |
| | A6 | EP 0 547 815 B1 | 03/12/1997 | EPO | | |
| | A7 | EP 0 261 799 A1 | 03/30/1988 | EPO | | |
| | A8 | FR 2 502 399 | 09/24/1982 | France | | Abstract only |
| | A9 | GB 2095904 | 10/06/1982 | Great Britain | | |
| | A10 | 02224336 | 09/06/1990 | Japan | | Abstract only |
| | A11 | 56105653 | 08/22/1981 | Japan | | Abstract only |

| EXAMINER INITIAL | OTHER ART – NON PATENT LITERATURE DOCUMENTS <small>(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.</small> | |
|---------------------|--|---|
| | A12 | Jang et al., "CrCu Based UBM (Under Bump Metallization) Study With Electroplated Pb/63Sn Solder Bumps-Interfacial Reaction and Bump Shear Strength," IEEE Transactions on Components and Packaging Technologies, Vol. 26, No. 1, March 2003, pp. 245-254. |
| | A13 | Reid et al., "Factors Influencing Damascene Feature Fill Using Copper PVD and Electroplating," <i>Solid State Technology</i> , July 2000, pp. 86-88, 92, 96, 98, 103. |

| | |
|-------------------------------------|-----------------|
| EXAMINER /Luan V. Van/ (03/02/2009) | DATE CONSIDERED |
|-------------------------------------|-----------------|

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /L.V./